



Final Product/Process Change Notification

Document #:FPCN25729X

Issue Date: 28 Mar 2024

Title of Change:	Wafer Fab Site Addition of onsemi, Bucheon Korea as alternate fab site for ESD and Surge Protection products.	
Proposed First Ship date:	05 Jul 2024 or earlier if approved by customer	
Contact Information:	Contact your local onsemi Sales Office or norhayati.othman@onsemi.com	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Additional Reliability Data:	Contact your local onsemi Sales Office or Nicky.Siu@onsemi.com	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com	
Marking of Parts/ Traceability of Change:	Changed material can be identified by lot code	
Change Category:	Wafer Fab Change	
Change Sub-Category(s):	Manufacturing Site Addition	
Sites Affected:		
onsemi Sites	External Foundry/Subcon Sites	
onsemi Bucheon, Korea	None	
Description and Purpose:		
<p>This Final Product Change Notification (FPCN) is to notify customers of the qualification of onsemi Bucheon, Korea Wafer Fab as an additional wafer fab site for ESD and Surge Protection products.</p> <p>Upon expiration of this FPCN, affected parts can be sourced from either onsemi Bucheon, Korea or LA Semiconductor wafer fab."</p>		
	Before Change Description	After Change Description
Manufacturing location for Wafer Fab	LA Semiconductor, Idaho, United States	onsemi Bucheon, Korea, LA Semiconductor, Idaho, United States



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Reliability Data Summary:

QV DEVICE NAME: ESD7321MUT5G

RMS: S94408

PACKAGE: X3DFN

Test	Specification	Condition	Interval	Results
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta=150°C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1@260°C		0/693
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
ESD8472BMUT5G	ESD7321MUT5G
ESD8472MUT5G	ESD7321MUT5G
ESD8472MUT3G	ESD7321MUT5G
ESD7321MUT5G	ESD7321MUT5G

Appendix A: Changed Products

PCN#: FPCN25729X
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DIKG: DIGI-KEY

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
ESD8472BMUT5G		ESD7321MUT5G	#NONE	
ESD8472MUT3G		ESD7321MUT5G	#NONE	
ESD8472MUT5G		ESD7321MUT5G	#NONE	